

# CP Series Thermal Cap



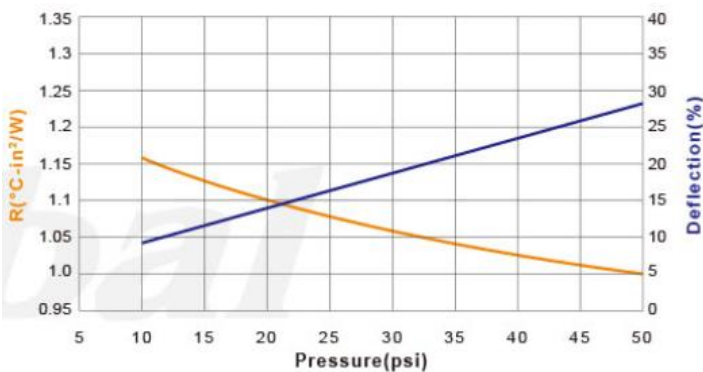
## Features

- Low thermal contact resistance
- Electrically isolating
- Decrease the weight of the product
- Easy to assemble
- Thermal conduction and buffer effect

## Applications

Electronic components: IC, CPU, MOS, LED, M/B, P/S, Heat Sink, LCD-TV, Notebook PC, PC, Telecom Device, Wireless Hub.....etc  
DDR II Module, DVD Applications, Hand-set applications.....etc

## Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R(°C-in <sup>2</sup> /W)	Deflection(%)
10	1.16	9
20	1.10	14
50	1.00	28

Testing sample thickness: 0.45mm

In "Thermal resistance V.S. Pressure V.S. Deflection" chart, CP Series provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower. CP Series provides good compliance and softness.

## Standard Sizes (mm)

1. CP22 TO-220: 11.4x16x5.8
2. CP23 TO-220: 11.4x21.5x5.8
3. CP33 TO-247: 17.5x28.5x5.8

Hardness: 75 (Shore A)



Properties	CP22/CP23/CP33	Unit	Tolerance	Test Method
Thermal Conductivity	1.9	W / mK	±0.19	ASTM D5470
Thickness	0.3/0.45	mm	-	ASTM D374
Color	Gray	-	-	Visual
Material	Silicone	-	-	-
Op. Temp. range	-45 to 180	°C	-	-
Density	2.55	g / cm <sup>3</sup>	-	ASTM D792
Breakdown Voltage AC	4 / 6	KV	±0.4 / ±0.6	ASTM D149
Breakdown Voltage DC	6 / 8	KV	±0.4 / ±0.8	ASTM D149
Dielectric Constant	5.8	1000Hz	-	ASTM D150
Thermal Impedance	-	-	-	-
t=0.3mm	10psi	1.16	°C - in <sup>2</sup> / W	ASTM D5470
	20psi	1.1	°C - in <sup>2</sup> / W	ASTM D5470
	50psi	1	°C - in <sup>2</sup> / W	ASTM D5470
TML	<0.2	%	-	ASTM E595
Hardness	75	Shore A	±7	ASTM E595

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

